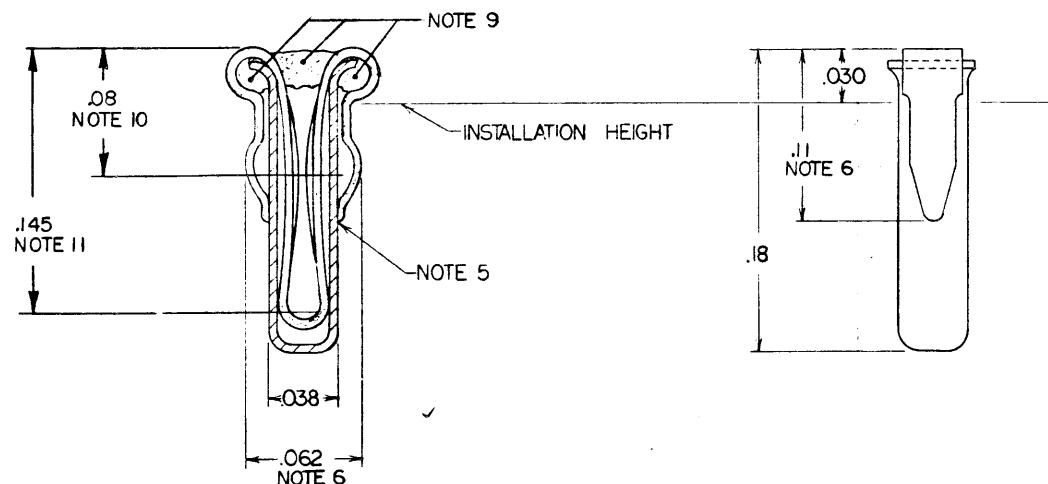
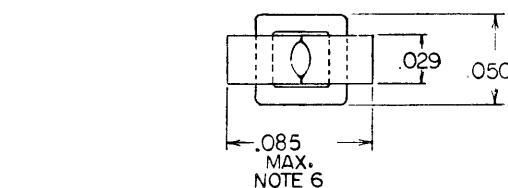


PRODUCT NO.	NOTE
75315-001	AS SHOWN

REVISIONS			
REV	DESCRIPTION	BY	DATE
F	REDRAWN	DEW	9-9-71
G	ADDED NOTE 10 ADD PIN -002	DCH	11-1-74
H		PER	4-30-85
J	DELETED -002, ADDED DIM'S .08+.145, REVISED NOTES 1,3,4,5,8,10 ADDED NOTE 11, DELETED DIMPLE ON DNG	DA	1- -25- -80
K	SPRING WIDTH .085 WAS .080	BMG	5/15/84

NOTES:

1. THE SOCKET ASSY SHALL BE SELF RETAINING DURING WAVE SOLDERING IN HOLES FROM .050 TO .058 DIA.
2. THE SPRING SHALL SOLDER TO THE CUP DURING WAVE SOLDERING IN SINGLE OR DOUBLE SIDED BOARDS TO 1/16 THK. NO SOLDER SHALL ENTER THE INSIDE OF THE CUP.
3. THE SOCKET SHALL ACCEPT ROUND LEADS FROM .012 TO .022 DIA. AND FLAT LEADS WHEN PROPERLY ORIENTED FROM .008 TO .015 THK. BY .020 TO .025 WIDE.
4. SEE PRODUCT SPEC 12-006 FOR INSERTION / WITHDRAWAL FORCES.



5. GAP BETWEEN SPRING TIPS AND CUP NOT TO EXCEED .003.

⑥ DIMENSIONS APPLY PRIOR TO INSTALLATION

7. CUP MATERIAL: GILDING MATERIAL PER MIL-C-21768. SPRING MATERIAL: B-Cu PER QQ-C-533.
8. CUP PLATING: TIN-LEAD 60/40 1,50 μ / 60 μ THK. SPRING PLATING: 0.76 μ / 30 μ GOLD (MIL G45204B) TYPE IC, OVER 1.01 μ / 40 μ NICKEL (QQ-N-290)

⑨ R.T.V. APPLIED TO AREA SHOWN TO PREVENT FLUX AND SOLDER FROM ENTERING SOCKET DURING WAVE SOLDERING.

⑩ SHOWS CENTER LINE OF THEORETICAL POINT OF CONTACT FROM TOP OF SPRING

⑪ SHOWS MAX. DEPTH FOR .020 LEAD FROM TOP OF SPRING

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NEXT ASSY			USED ON		DO NOT SCALE DRAWING		TOLERANCES UNLESS OTHERWISE NOTED		INCH	MM	REV	NOTES	DATE
					◆	+	LINEAR	.00±			CKD	NOTE 7	9-9-71
								.000±.008					
					◆	+	THIRD ANGLE PROJECTION	RADI			ENGR	FINISH	NOTE 8
											APP	APP	9-24-71
					◆	+	APPLICATION	INCH					
								MM					
								ANGLES					

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PDM: Rev.K STATUS: Released

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